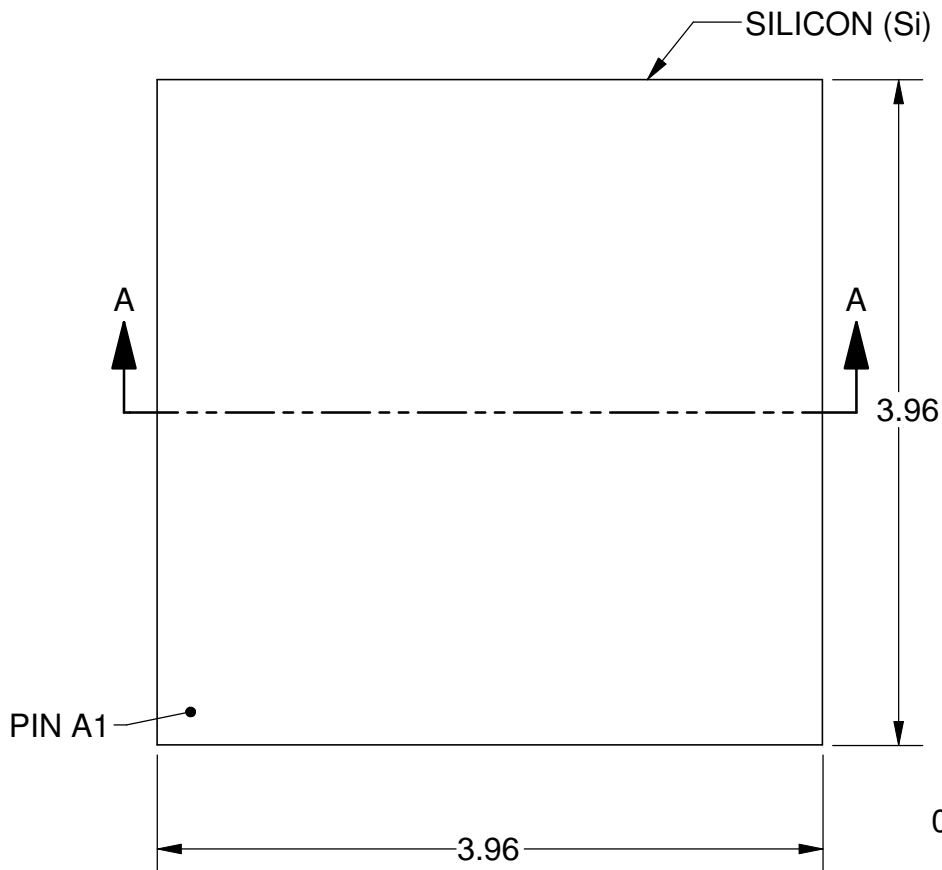
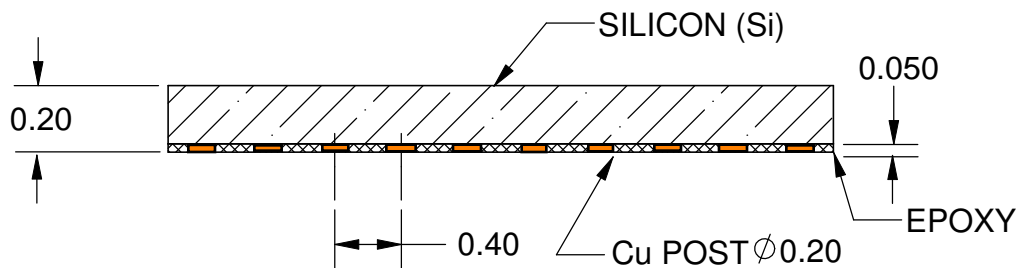
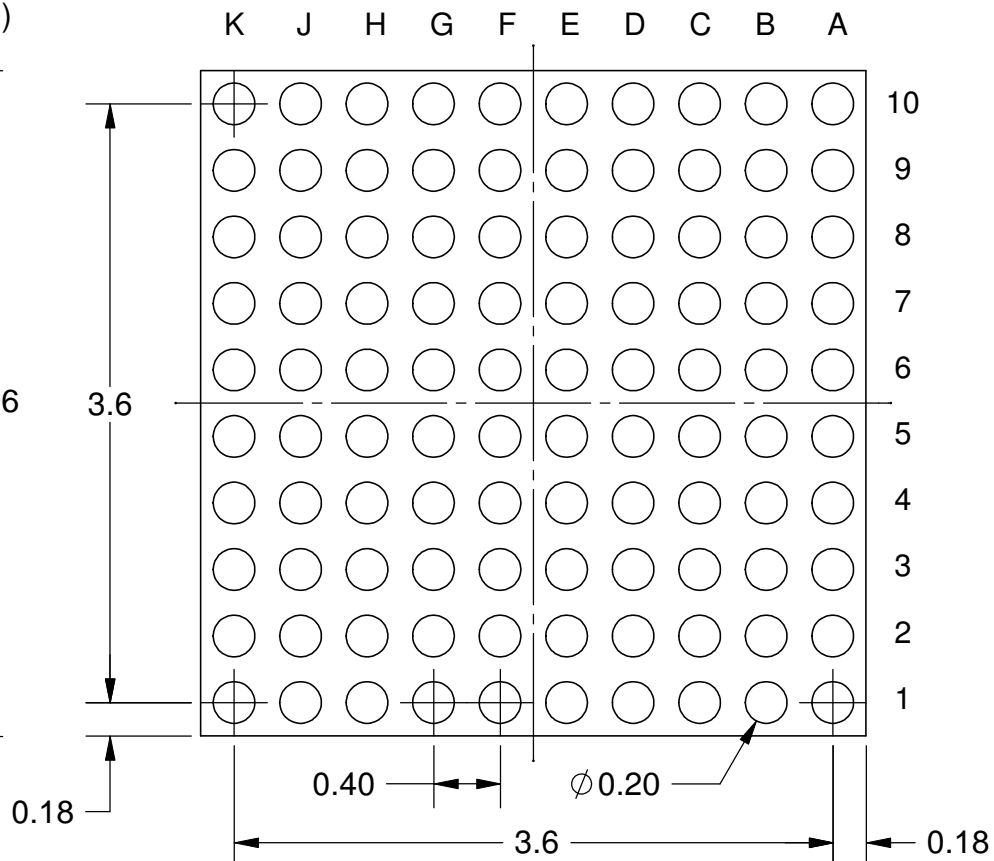


TOP VIEW



PAD VIEW



SECTION A-A

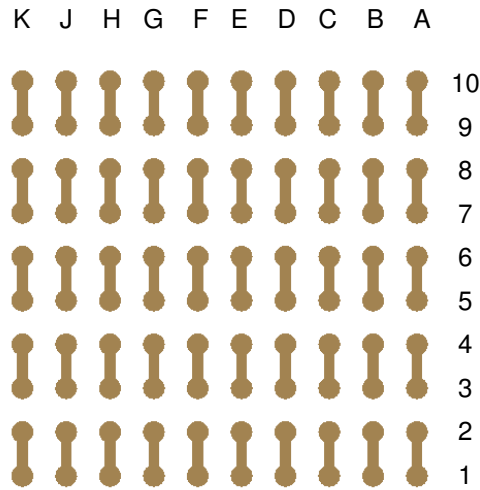
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) PAD ALLOY: Cu Post (50um Thick)
- 3) PAD Cu DIAMETER: 0.20mm.
- 4) DIE MATERIAL: Si (SILICON).
- 5) DAISY CHAIN PATTERN (SEE PAGE 2).

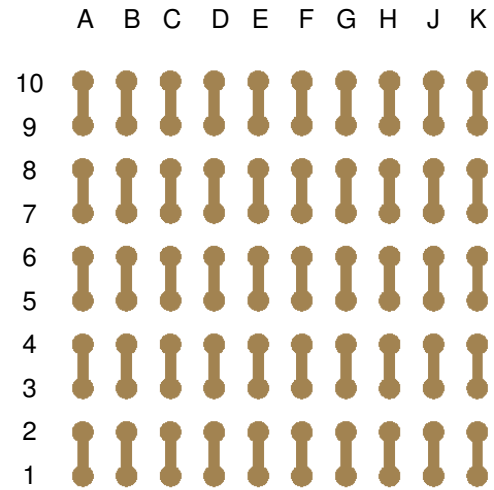
TOLERANCE UNLESS NOTED		APPROVALS		DATE		TopLine [®]				
X.X	+/- 0.3	DRAWN J. Hines		12/30/2010						TITLE eWLP100T.4-DC108D 100-L P=0.4mm (TEG0408)
X.XX	+/- 0.03	ENG				SCALE		SIZE	DRAWING NO.	
X.XXX	+/- 0.003	MFG				22:1		A	641080	A
ANGLES +/- 0.5°		QA				DO NOT SCALE DRAWING		SHEET 1 OF 2		
ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		CUST								
THIRD ANGLE PROJECTION		REVISED								

DAISY CHAIN PATTERN

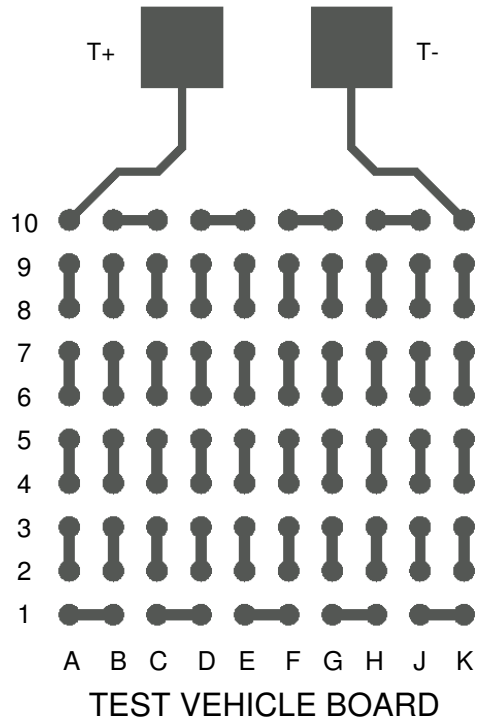
PAD VIEW



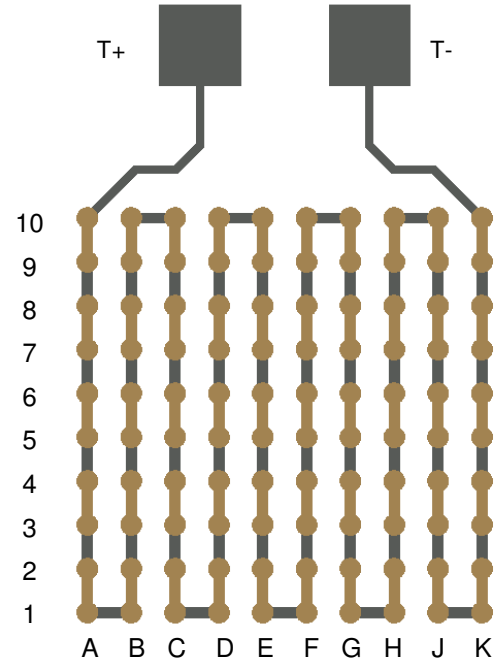
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine ®			
TITLE eWLP100T.4-DC108D 100-BALL P=0.4mm (TEG0408)			
SCALE 14.5:1	SIZE A	DRAWING NO. 641080	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	